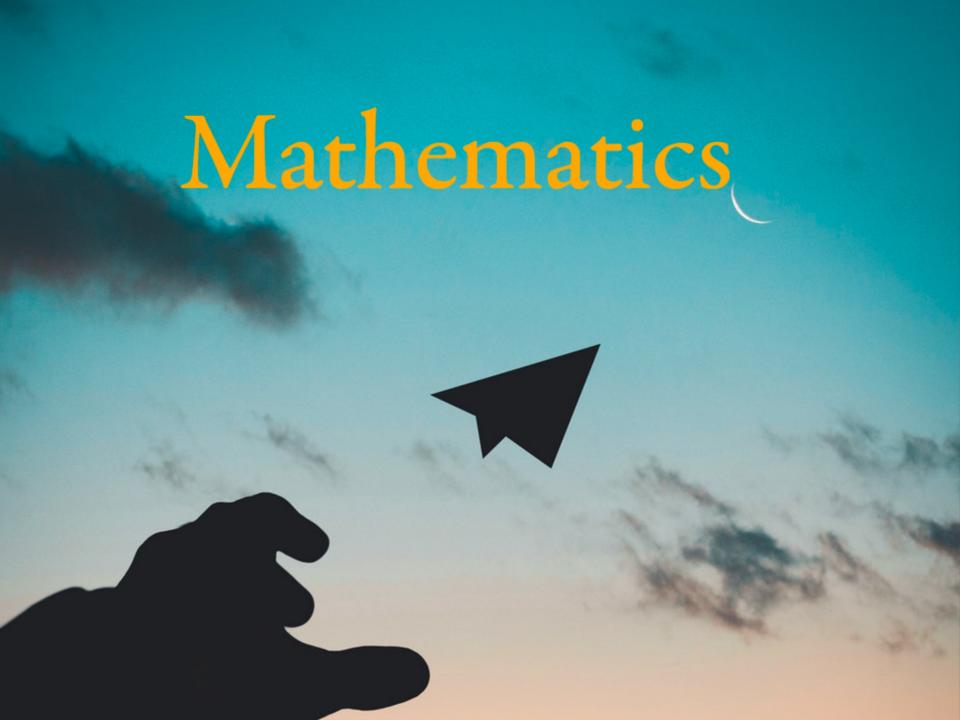
Fundamentals of Physics of Failure

Fred Schenkelberg



Root Cause





Is there a model for the applied stress of

85RH/85°C?

Physics of Failure



Models

Mechanisms

Use

PoF Models



"All models are wrong... but some are useful." George Box

A science based approach using modeling and simulation

Based on knowledge of root causes of failure mechanisms

Emperical or Deterministic?

Focus on Mechanisms



Root cause - at fundamental level

Fundamental physical and chemical behavior of materials to reliability parameters - Wikipedia

Is modeling warranty returns a PoF model?

PoF Use



Having a model is nice, using it is great

Models are not like hammers

Need good information - GIGO

- Decision support / what if analysis
- Avoid or minimize accelerated testing

What else is a good use of PoF?

How do you explain

physics of failure and reliability?

Finding Existing PoF Models









Literature

WARP

CALCE

DFR Solutions









What mechanisms

would you like to model?

Creating a PoF Model







Concept

Research Project

Degree

Conceptually



It's a model, just because you can make it more complex, should you?

Objective - estimate time to failure

Approach - stress(es) influence on TTF

Relationships - experimental work

Modeling - mathematics, simulation

Check step - how accurate is the model

Refine - improve with better data

Do a Research Project



If the value of model is high, this makes sense

Deep dive on specific mechanism

Which mechanisms to model?

Earn an Advanced Degree



You will finally have a doctor in the family

This is going back to school.

- + Lab equipment
- + Guideance and Reviews
- Rigor
- Published

Is it worth having

and using a PoF model?

Example PoF Models







Electromigration Wire Bonds Solder Joints

Electromigration



Black's Equation

$$TTF = A(J^{-n})e^{\frac{Ea}{kT}}$$

A is a constant based on cross-sectional area
J is the current density
Ea is the activation energy k is Boltzmann constant
T is temperature
n is a scaling factor

Temperature & Humidity on Wire bond attach



Pecks equation for wire bond/ bond pad connections

$$TTF = A_0 (RH^{-2.7}) f(V) \exp\left(\frac{E_a}{kT}\right)$$

A is a constant, RH is the relative humidity, f(V) is a voltage function (often cited as voltage squared), Ea is the activation energy, k is Boltzmann's constant, and T is temperature in Kelvin

Vibration & Solder Joints



Steinberg – has many models describing vibation effect on structures

$$Z_0 = \frac{9.8 \times 3\sqrt{\pi/2 \times PSD \times f_n \times Q}}{f_n^2}$$

$$Z_0 = \frac{0.00022B}{0.00022B}$$

$$Z_c = rac{0.00022E}{chr\sqrt{L}}$$

Z is maximum displacement, PSD is the power spectral density (g2/Hz), fn is the natural frequency of the CCA, O is transmissibility (assumed to be square re

Q is transmissibility (assumed to be square root of natural frequency),

Zc is the critical displacement (20 million cycles to failure), B is the length of PCB edge parallel to component located at the center of the board,

c is a component packaging constant, h is PCB thickness, r is a relative position factor, and L is component length.

How have you made

made use of models?

In Summary

An Approach



Models Models



Useful











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